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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of:

Minoru UESHIMA

Application No.: 10/594,577

International Application No. PCT/JP2005/006809

International filing date: March 31, 2005

For: POURING APPARATUS FOR MOLTEN METAL AND CASTING METHOD

INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Pursuant to the requirements of 37 CFR §§1.56 and 1.97, the attention of the Examiner is directed to the documents listed on the attached Form PTO-1449. Copies of the listed documents which are not U.S. patent documents are attached. Neither this Statement nor the listing of these documents on Form PTO-1449 is an admission that these documents are prior art as to the Applicant or a representation that a search has been made or that no more pertinent documents exist.

The Applicant respectfully requests that the listed documents be considered by the Examiner and made of record in the

referenced patent application.

Respectfully submitted,

A handwritten signature in cursive script that reads "Michael Tobias".

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Date: June 15, 2007

Form PTO-1449 (modified)
List of Patent and Publications For
Applicant's Information Disclosure
Statement
(use several sheets if necessary)

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Atty. Docket. No.:
1092

Appln. No.:
10/594,577

Applicant:
Minoru Ueshima

Intl. Filing Date:
March 31, 2005

Art Unit:

U.S. PATENT DOCUMENTS

Exr's Initial		Document No.							Date	Name	Class	Sub class	Filing Date
	AA	3	4	0	1	1	2	6	9/10/68	Miller et al	252	514	6/18/65
	AB	2003	0	8	5	2	5	3	5/8/03	Shimizu et al	228	56.3	10/15/02
	AC												
	AD												
	AE												
	AF												
	AG												
	AJ												

FOREIGN PATENT DOCUMENTS

		Document No.							Date	Country	Class	Sub class	Translation	
													Yes	No
	AK													
	AL													
	AM													
	AN													
	AO													

OTHER ART (Including author, title, date pertinent pages, etc.)

	AP	CHI-WON HWANG ET AL: "Joint reliability and high temperature stability of Sn-Ag-Bi lead-free solder with Cu and Sn-Pb/Ni/Cu substrates", published in MATERIALS SCIENCE & ENGINEERING A (STRUCTURAL MATERIALS: PROPERTIES, MICROSTRUCTURE AND PROCESSING), vol. A373, no. 1 - 2 (May 25, 2004), pages 187 - 194, XP-002427195
	AQ	
	AR	

Examiner

Date considered:

EXAMINER: Initial if reference considered, no matter whether citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.